

XL-DZ304UGD/4

技术数据表 Technical Data Sheet

F3MM 绿发绿四孔灯座

特点 (characteristic) :

* :20.3*10.7*4.5mm

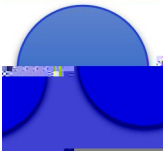
Appearance dimension : 20.

col 1/ 0 4

co lpi 3:

co bw

*





电性参数

Electrical Characteristics

Absolute Maximum Ratings Ta=25

Max Power Dissipation	PD	240	mW
Max Continuous Forward Current	IF	20*4=80	mA
Peak Forward Current	IFP	80*4=320	mA
Max Reverse Voltage	VR	5	V
Antistatic ability	ESD	2000	V
Operating Temperature Range	TOPR	-40 ~ +85	
Storage Temperature Range	TSTR	-40 ~ +85	
/ Lead Soldering Temperature/Time	TSOL	260 6S	/S

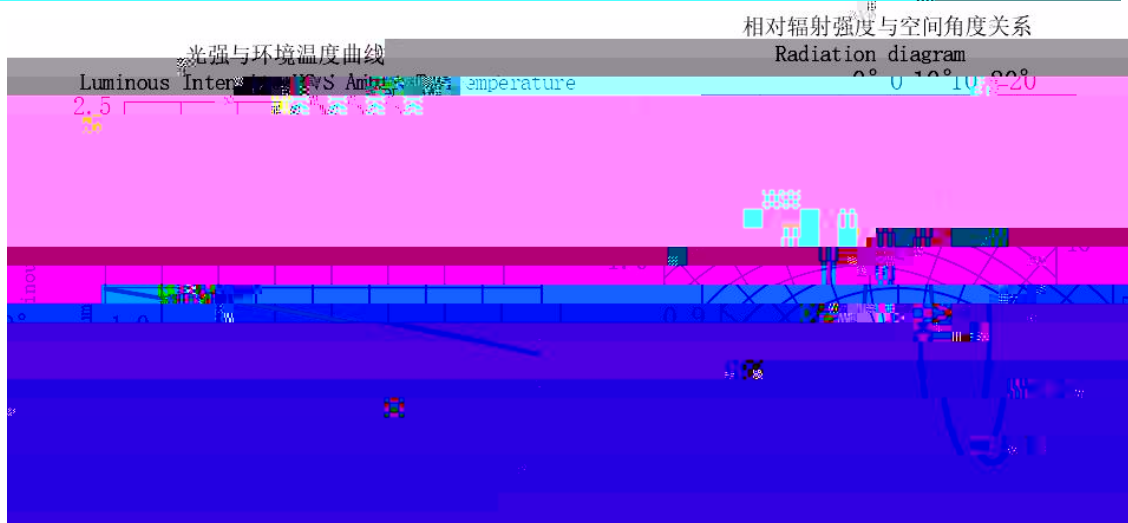
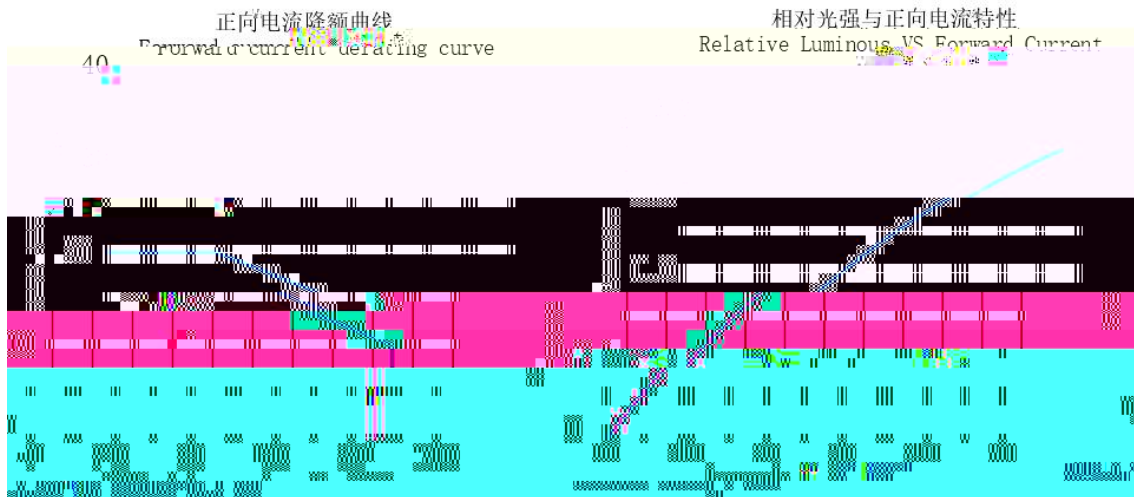
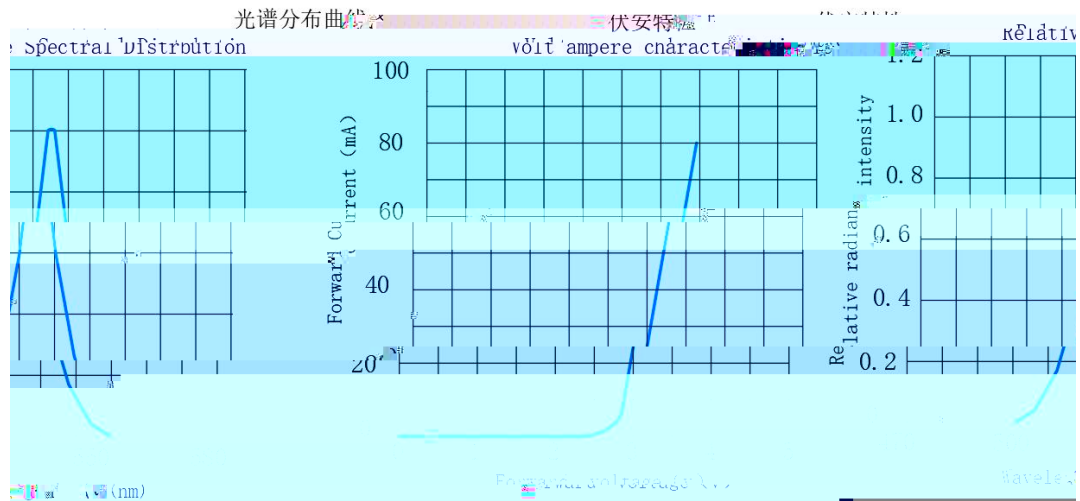
Initial Electrical Optical Characteristics Ta=25

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions
Luminous Intensity	Iv	/	5000	/	mcd	IF=20mA
Dominant Wave Length	λd	515	/	530	nm	IF=20mA
Peak Wave Length	λp	/	525	/	nm	IF=20mA
Forward Voltage	VF	2.6	/	3.4	V	IF=20mA
Half wave width	Δλ	/	30	/	nm	IF=20mA
Viewing Angle	2θ1/2	/	50°	/	deg	IF=20mA
Reverse Current	IR	/	/	0.5	μA	VR=5V

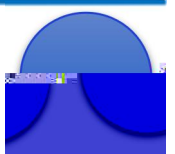


典型特性曲线

Typical Characteristics Curves



25 ± 5 °C./Note: If not otherwise indicated, the test environment temperature is 25 ± 5 °C.



可靠性试验

Reliability Test Items And Conditions

Class	Test item	Testing environment	Testing time	Qty	Fail qty





包装

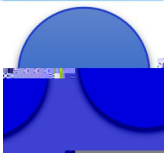
Packaging

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In Bags

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Moisture Proof and Anti-Electrostatic Foil Bag



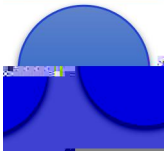
使用注意事項 ()

Precautions (1)

1、貯蔵

Storage

St



使用注意事項 ()

設計建議

Design Consideration

LED

A

LED

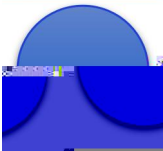
B

LED

V_F

LED

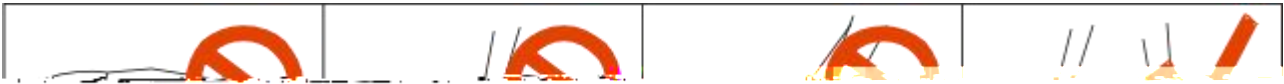
In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. In the



4、其他事项:

Others

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant will cause catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED

The epoxy resin encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.